

2 A, 1.2 V, Slew Rate Controlled Load Switch

DESCRIPTION

The SiP32411 is a slew rate controlled load switch that is designed for 1.1 V to 5.5 V operation.

The device guarantees low switch on-resistance at 1.2 V input. It features a controlled soft-on slew rate of typical 150 μ s that limits the inrush current for designs of capacitive load or noise sensitive loads.

The device features a low voltage control logic interface (on/off interface) that can interface with low voltage digital control without extra level shifting circuit. It also integrates an output discharge switch that enables fast shutdown load discharge. When the switch is off, it provides the reverse blocking to prevent high current flowing into the power source.

The SiP32411DN is in TDFN4 package of 1.2 mm by 1.6 mm. It supports over 2 A of continuous current. The SiP32411DR is in SC-70-6 package.

FEATURES

- 1.1 V to 5.5 V operation voltage range
- 62 m Ω typical from 2 V to 5 V for SiP32411DN
- 101 m Ω typical from 2 V to 5 V for SiP32411DR
- Low R_{ON} down to 1.2 V
- Slew rate controlled turn-on: 150 μ s at 3.6 V
- Fast shutdown load discharge
- Low quiescent current
< 1 μ A when disabled
6.7 μ A at V_{IN} = 1.2 V
- Switch off reversed blocking
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



APPLICATIONS

- Cellular phones
- Portable media players
- Digital camera
- GPS
- Computers
- Portable instruments and healthcare devices

TYPICAL APPLICATION CIRCUIT

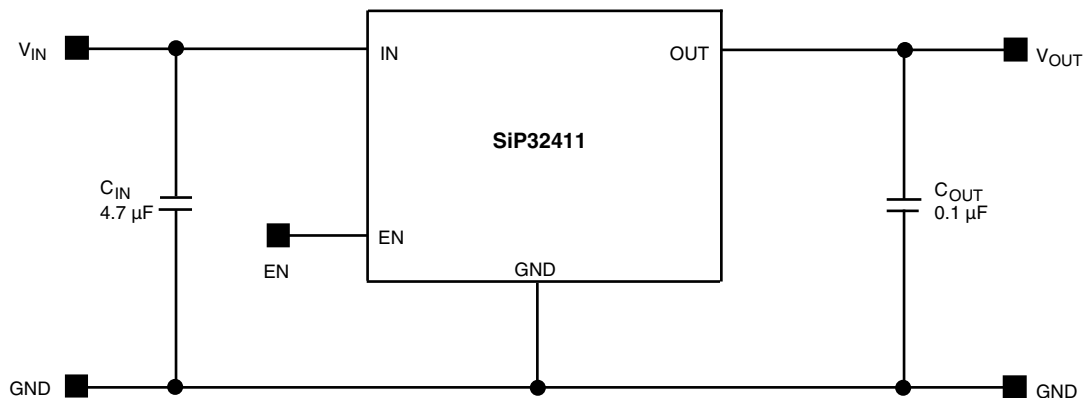


Fig. 1 - SiP32411 Typical Application Circuit

| ORDERING INFORMATION | | | |
|----------------------|-----------------------|---------|--------------------|
| TEMPERATURE RANGE | PACKAGE | MARKING | PART NUMBER |
| -40 °C to 85 °C | SC-70-6 | MBxx | SiP32411DR-T1-GE3 |
| | TDFN4 1.2 mm x 1.6 mm | Ex | SiP32411DNP-T1-GE4 |

Notes

- x = lot code
- -GE3 and -GE4 denotes halogen-free and RoHS-compliant



| ABSOLUTE MAXIMUM RATINGS | | | |
|---|--|------------------------|------|
| PARAMETER | | LIMIT | UNIT |
| Supply input voltage (V_{IN}) | | -0.3 to 6 | V |
| Enable input voltage (V_{EN}) | | -0.3 to 6 | |
| Output voltage (V_{OUT}) | | -0.3 to $V_{IN} + 0.3$ | |
| Maximum continuous switch current ($I_{max.}$) | SC-70-6 package | 1.8 | A |
| | TDFN4 1.2 mm x 1.6 mm | 2.4 | |
| Maximum pulsed current (I_{DM}) V_{IN} (pulsed at 1 ms, 10 % duty cycle) | SC-70-6 package | 2.2 | |
| | TDFN4 1.2 mm x 1.6 mm | 3 | |
| ESD rating (HBM) | | 4000 | V |
| Junction temperature (T_J) | | -40 to +125 | °C |
| Thermal resistance (θ_{JA}) ^a | 6 pin SC-70-6 ^b | 240 | °C/W |
| | 4 pin TDFN4 1.2 mm x 1.6 mm ^c | 170 | |
| Power dissipation (P_D) ^a | 6 pin SC-70-6 ^b | 230 | mW |
| | 4 pin TDFN4 1.2 mm x 1.6 mm ^c | 324 | |

Notes

- a. Device mounted with all leads and power pad soldered or welded to PC board, see PCB layout
- b. Derate 4.5 mW/°C above $T_A = 70$ °C, see PCB layout
- c. Derate 5.9 mW/°C above $T_A = 70$ °C, see PCB layout

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating/conditions for extended periods may affect device reliability.

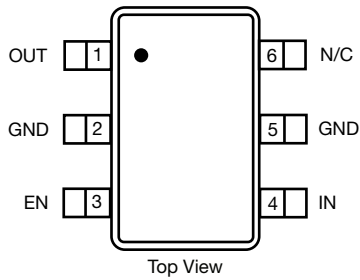
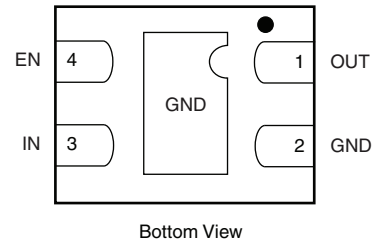
| RECOMMENDED OPERATING RANGE | | |
|----------------------------------|------------|------|
| PARAMETER | LIMIT | UNIT |
| Input voltage range (V_{IN}) | 1.1 to 5.5 | V |
| Operating temperature range | -40 to 85 | °C |



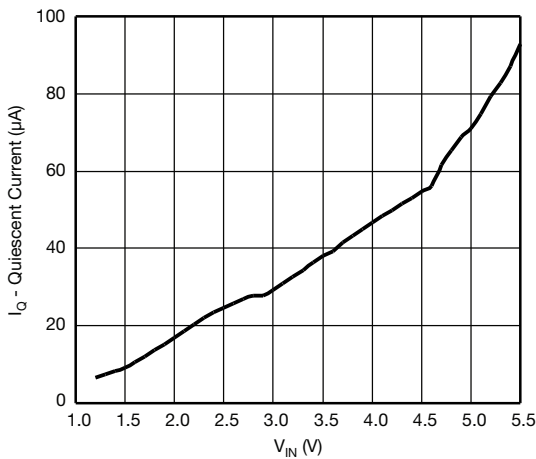
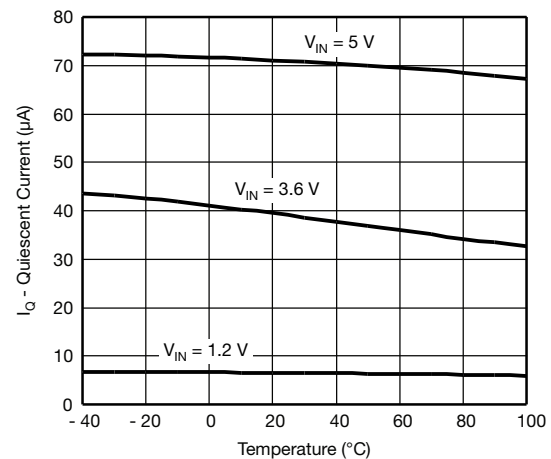
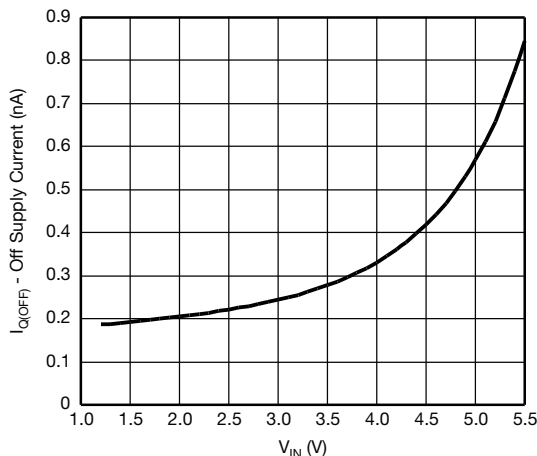
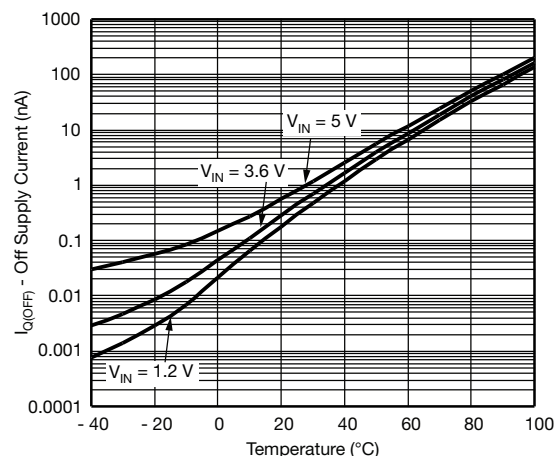
| SPECIFICATIONS | | | | | | | |
|---------------------------------------|----------------------|---|--|-------------------|-------------------|-------------------------------|------------------|
| PARAMETER | SYMBOL | TEST CONDITIONS UNLESS SPECIFIED $V_{IN} = 5, T_A = -40\text{ }^{\circ}\text{C to } 85\text{ }^{\circ}\text{C}$ (Typical values are at $T_A = 25\text{ }^{\circ}\text{C}$) | LIMITS -40 °C TO 85 °C | | | UNIT | |
| | | | MIN. ^a | TYP. ^b | MAX. ^a | | |
| Operating voltage ^c | V_{IN} | | 1.5 | - | 5.5 | V | |
| Quiescent current | I_Q | $V_{IN} = 1.2\text{ V}, EN = \text{active}$ | - | 6.7 | 14 | μA | |
| | | $V_{IN} = 1.8\text{ V}, EN = \text{active}$ | - | 14 | 24 | | |
| | | $V_{IN} = 2.5\text{ V}, EN = \text{active}$ | - | 25 | 40 | | |
| | | $V_{IN} = 3.6\text{ V}, EN = \text{active}$ | - | 40 | 60 | | |
| | | $V_{IN} = 4.3\text{ V}, EN = \text{active}$ | - | 52 | 75 | | |
| Off supply current | $I_{Q(\text{off})}$ | EN = inactive, OUT = open | - | - | 1 | | |
| Off switch current | $I_{DS(\text{off})}$ | EN = inactive, OUT = GND | - | - | 1 | | |
| Reverse blocking current | I_{RB} | $V_{OUT} = 5\text{ V}, V_{IN} = 1.2\text{ V}, V_{EN} = \text{inactive}$ | - | - | 10 | | |
| On-resistance | $R_{DS(\text{on})}$ | SC-70-6 | $V_{IN} = 1.2\text{ V}, I_L = 100\text{ mA}, T_A = 25\text{ }^{\circ}\text{C}$ | - | 105 | 125 | $\text{m}\Omega$ |
| | | | $V_{IN} = 1.8\text{ V}, I_L = 100\text{ mA}, T_A = 25\text{ }^{\circ}\text{C}$ | - | 101 | 120 | |
| | | | $V_{IN} = 2.5\text{ V}, I_L = 100\text{ mA}, T_A = 25\text{ }^{\circ}\text{C}$ | - | 101 | 120 | |
| | | | $V_{IN} = 3.6\text{ V}, I_L = 100\text{ mA}, T_A = 25\text{ }^{\circ}\text{C}$ | - | 101 | 120 | |
| | | | $V_{IN} = 4.3\text{ V}, I_L = 100\text{ mA}, T_A = 25\text{ }^{\circ}\text{C}$ | - | 101 | 120 | |
| | | | $V_{IN} = 5\text{ V}, I_L = 100\text{ mA}, T_A = 25\text{ }^{\circ}\text{C}$ | - | 101 | 120 | |
| | | TDFN4 1.2 mm x 1.6 mm | $V_{IN} = 1.2\text{ V}, I_L = 100\text{ mA}, T_A = 25\text{ }^{\circ}\text{C}$ | - | 66 | 76 | |
| | | | $V_{IN} = 1.8\text{ V}, I_L = 100\text{ mA}, T_A = 25\text{ }^{\circ}\text{C}$ | - | 62 | 72 | |
| | | | $V_{IN} = 2.5\text{ V}, I_L = 100\text{ mA}, T_A = 25\text{ }^{\circ}\text{C}$ | - | 62 | 72 | |
| | | | $V_{IN} = 3.6\text{ V}, I_L = 100\text{ mA}, T_A = 25\text{ }^{\circ}\text{C}$ | - | 62 | 72 | |
| | | | $V_{IN} = 4.3\text{ V}, I_L = 100\text{ mA}, T_A = 25\text{ }^{\circ}\text{C}$ | - | 62 | 72 | |
| | | | $V_{IN} = 5\text{ V}, I_L = 100\text{ mA}, T_A = 25\text{ }^{\circ}\text{C}$ | - | 62 | 72 | |
| On-resistance temperature coefficient | TC_{RDS} | SC-70-6 package | - | 4300 | - | $\text{ppm}/^{\circ}\text{C}$ | |
| | | TDFN4 1.2 mm x 1.6 mm package | - | 3400 | - | | |
| EN input low voltage ^c | V_{IL} | $V_{IN} = 1.2\text{ V}$ | - | - | 0.3 | V | |
| | | $V_{IN} = 1.8\text{ V}$ | - | - | 0.4 ^d | | |
| | | $V_{IN} = 2.5\text{ V}$ | - | - | 0.5 ^d | | |
| | | $V_{IN} = 3.6\text{ V}$ | - | - | 0.6 ^d | | |
| | | $V_{IN} = 4.3\text{ V}$ | - | - | 0.7 ^d | | |
| | | $V_{IN} = 5\text{ V}$ | - | - | 0.8 ^d | | |
| EN input high voltage ^c | V_{IH} | $V_{IN} = 1.2\text{ V}$ | 0.9 ^d | - | - | V | |
| | | $V_{IN} = 1.8\text{ V}$ | 1.2 ^d | - | - | | |
| | | $V_{IN} = 2.5\text{ V}$ | 1.4 ^d | - | - | | |
| | | $V_{IN} = 3.6\text{ V}$ | 1.6 ^d | - | - | | |
| | | $V_{IN} = 4.3\text{ V}$ | 1.7 ^d | - | - | | |
| | | $V_{IN} = 5\text{ V}$ | 1.8 | - | - | | |
| EN Input leakage | I_{SINK} | $V_{EN} = 5.5\text{ V}$ | -1 | - | 1 | μA | |
| Output pull-down resistance | R_{PD} | EN = inactive, $T_A = 25\text{ }^{\circ}\text{C}$ | - | 217 | 280 | Ω | |
| Output turn-on delay time | $t_{d(\text{on})}$ | $V_{IN} = 3.6\text{ V}, R_{\text{load}} = 10\text{ }\Omega, T_A = 25\text{ }^{\circ}\text{C}$ | - | 140 | 210 | μs | |
| Output turn-on rise time | $t_{(\text{on})}$ | | 80 | 150 | 220 | | |
| Output turn-off delay time | $t_{d(\text{off})}$ | | - | 0.27 | 1 | | |

Notes

- a. The algebraic convention whereby the most negative value is a minimum and the most positive a maximum
- b. Typical values are for DESIGN AID ONLY, not guaranteed nor subject to production testing
- c. For V_{IN} outside this range consult typical EN threshold curve
- d. Not tested, guarantee by design

PIN CONFIGURATION

Fig. 2 - SC-70-6 Package

Fig. 3 - TDFN4 1.2 mm x 1.6 mm Package

| PIN DESCRIPTION | | | |
|-----------------|-------|------|--|
| PIN NUMBER | | NAME | FUNCTION |
| SC-70-6 | TDFN4 | | |
| 4 | 3 | IN | This pin is the n-channel MOSFET drain connection. Bypass to ground through a 2.2 μF capacitor |
| 2, 5 | 2 | GND | Ground connection |
| 3 | 4 | EN | Enable input |
| 1 | 1 | OUT | This pin is the n-channel MOSFET source connection. Bypass to ground through a 0.1 μF capacitor |

TYPICAL CHARACTERISTICS (internally regulated, 25 °C, unless otherwise noted)

Fig. 4 - Quiescent Current vs. Input Voltage

Fig. 6 - Quiescent Current vs. Temperature

Fig. 5 - Off Supply Current vs. Input Voltage

Fig. 7 - Off Supply Current vs. Temperature

TYPICAL CHARACTERISTICS (internally regulated, 25 °C, unless otherwise noted)

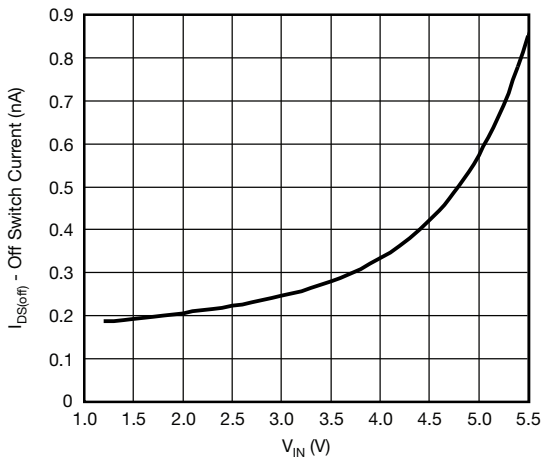


Fig. 8 - Off Switch Current vs. Input Voltage

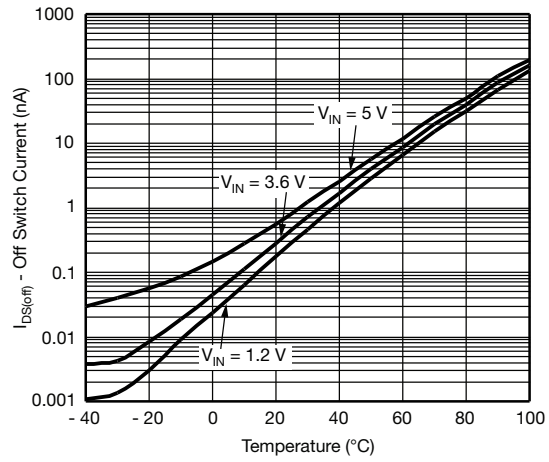


Fig. 11 - Off Switch Current vs. Temperature

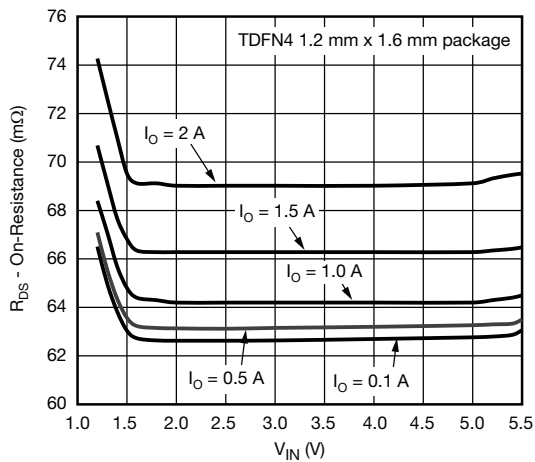


Fig. 9 - $R_{DS(on)}$ vs. V_{IN} for TDFN4 package

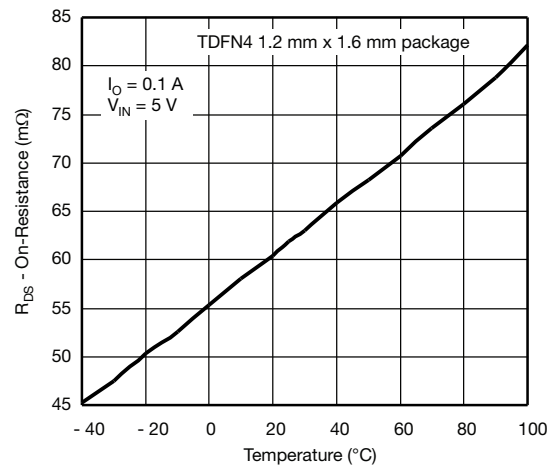


Fig. 12 - $R_{DS(on)}$ vs. Temperature for TDFN4 package

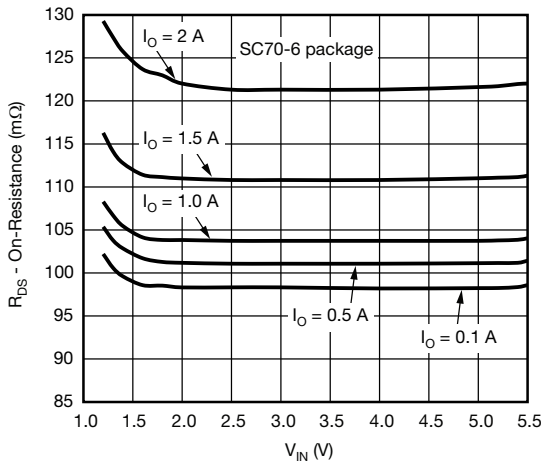


Fig. 10 - $R_{DS(on)}$ vs. V_{IN} for SC-70-6 package

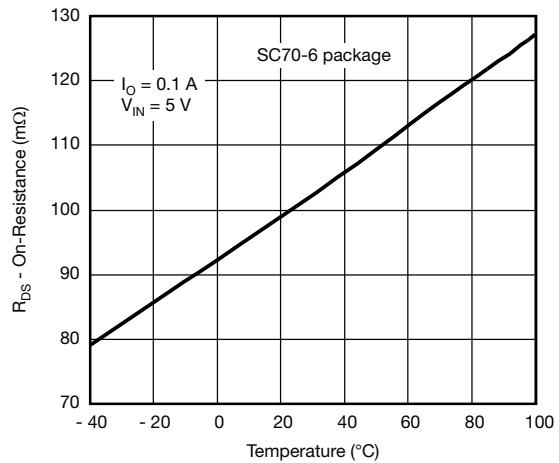


Fig. 13 - $R_{DS(on)}$ vs. Temperature for SC-70-6 package

TYPICAL CHARACTERISTICS (internally regulated, 25 °C, unless otherwise noted)

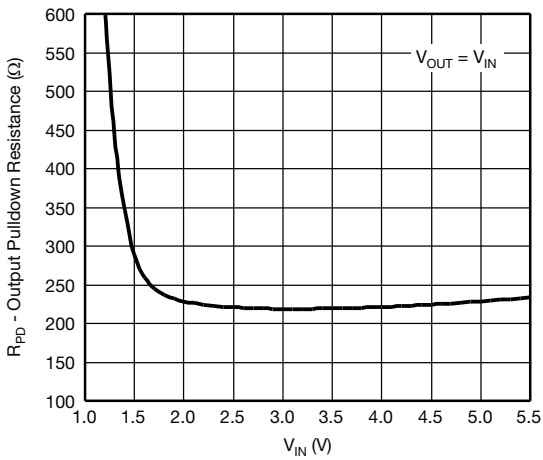


Fig. 14 - Output Pull Down vs. Input Voltage

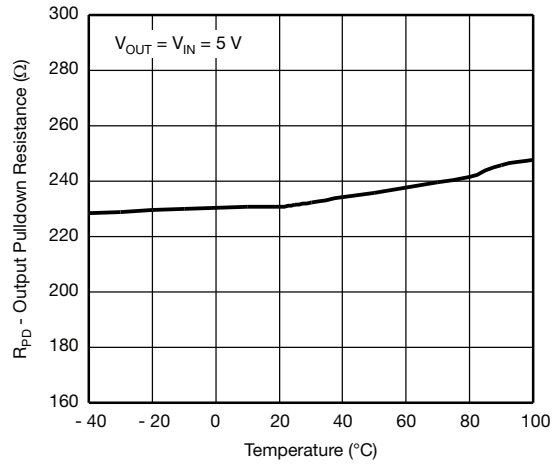


Fig. 17 - Output Pull Down vs. Temperature

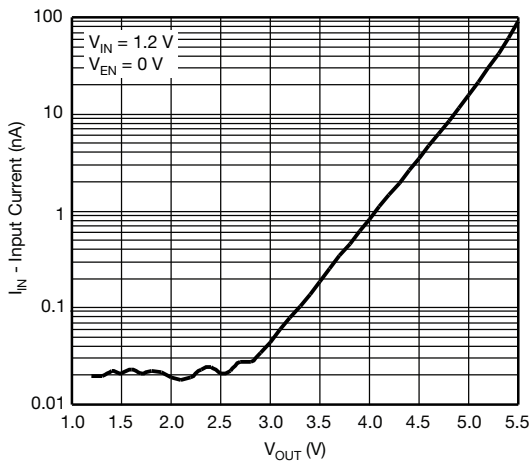


Fig. 15 - Reverse Blocking Current vs. Output Voltage

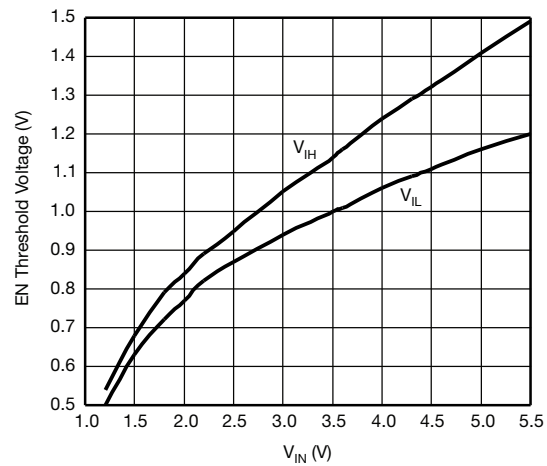


Fig. 18 - EN Threshold Voltage vs. Input Voltage

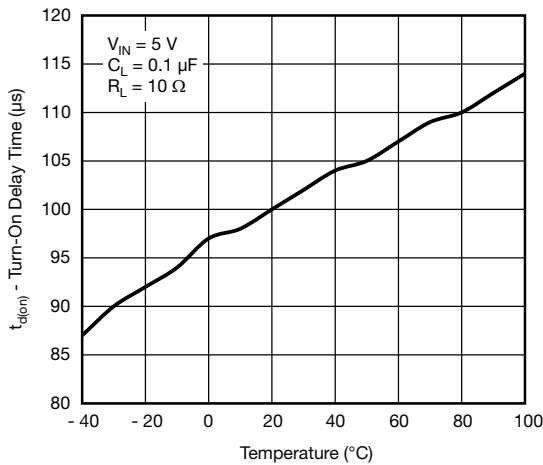


Fig. 16 - Turn-On Delay Time vs. Temperature

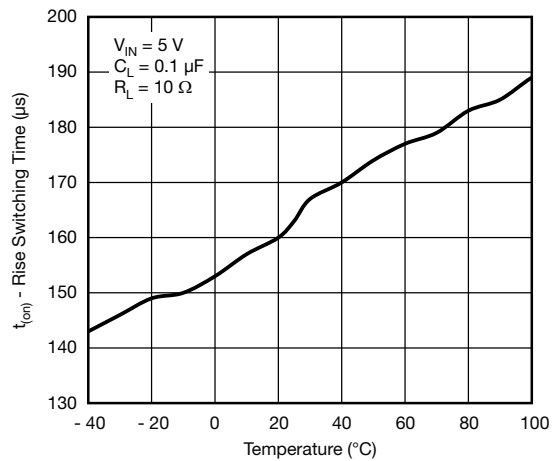


Fig. 19 - Rise Time vs. Temperature

TYPICAL CHARACTERISTICS (internally regulated, 25 °C, unless otherwise noted)

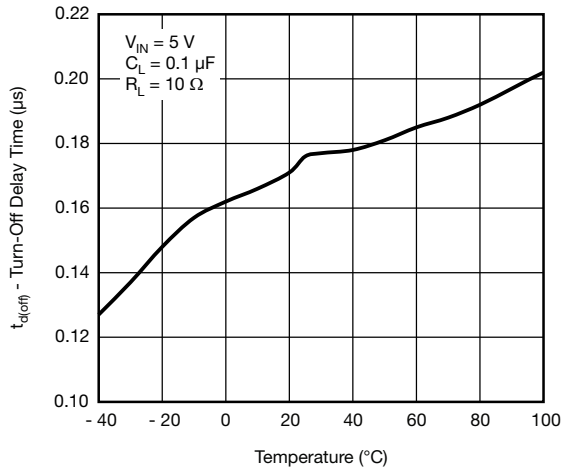


Fig. 20 - Turn-Off Delay Time vs. Temperature

TYPICAL WAVEFORMS

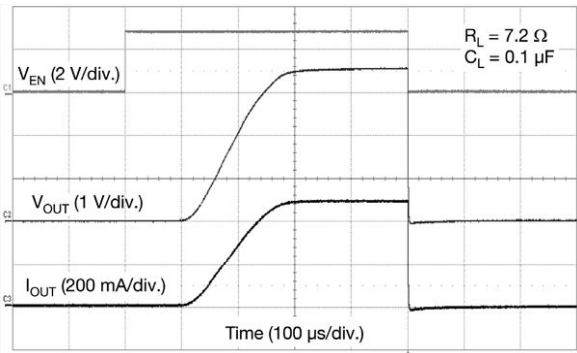


Fig. 21 - Switching ($V_{IN} = 3.6 V$)

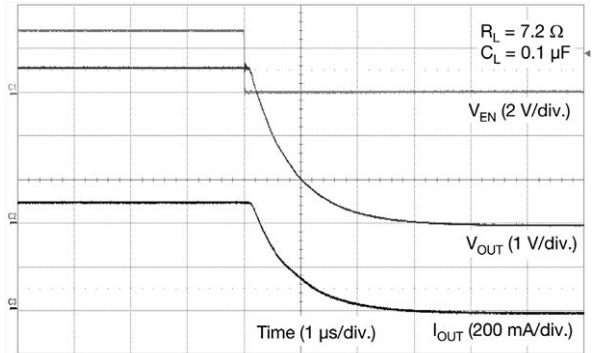


Fig. 23 - Turn-Off ($V_{IN} = 3.6 V$)

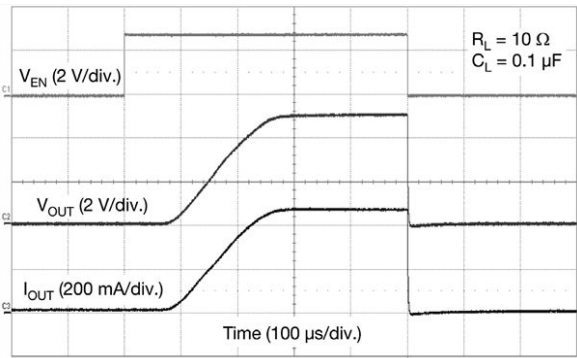


Fig. 22 - Switching ($V_{IN} = 5 V$)

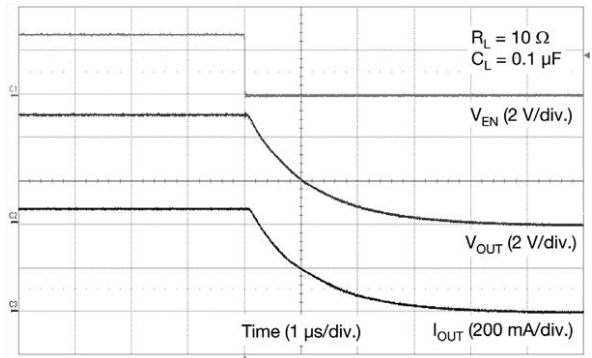


Fig. 24 - Turn-Off ($V_{IN} = 5 V$)

BLOCK DIAGRAM

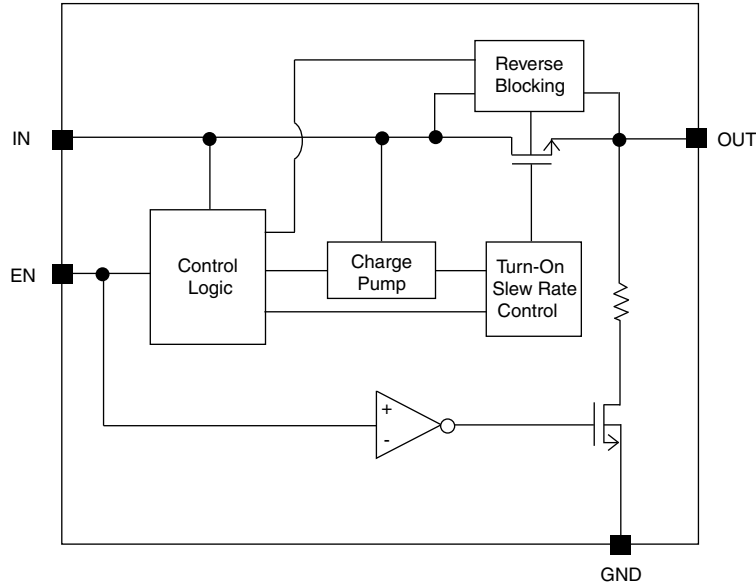


Fig. 25 - Functional Block Diagram

PCB LAYOUT

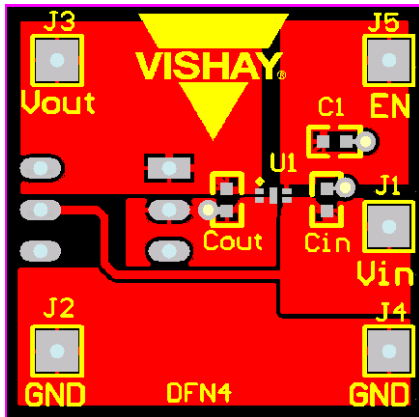


Fig. 26 - Top, PCB Layout for TDFN4 1.2 mm x 1.6 mm (board size: 1" x 1")

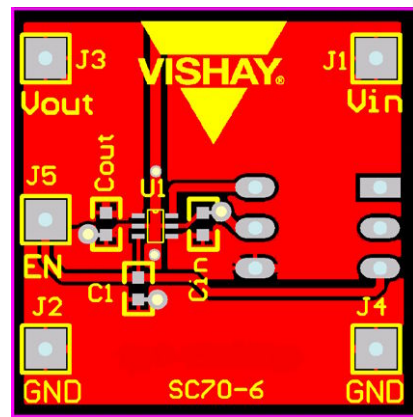


Fig. 28 - Top, PCB Layout for SC-70-6 (board size: 1" x 1")

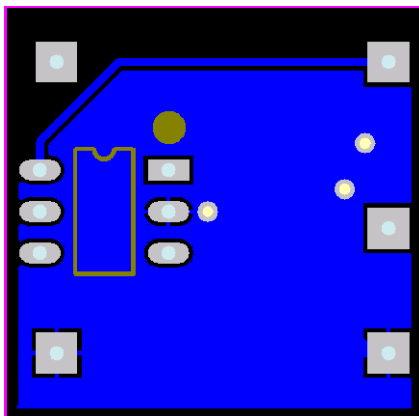


Fig. 27 - Bottom, PCB Layout for TDFN4 1.2 mm x 1.6 mm (board size: 1" x 1")

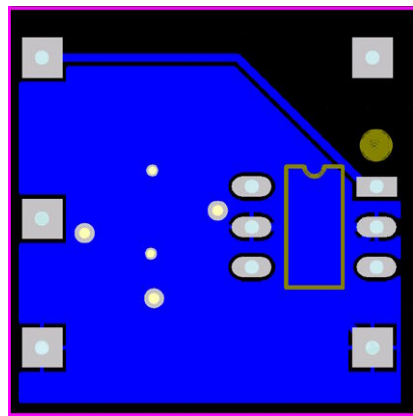


Fig. 29 - Bottom, PCB Layout for SC-70-6 (board size: 1" x 1")



DETAILED DESCRIPTION

SiP32411 is an n-channel power MOSFET designed as high side load switch with slew rate control to prevent in-rush current. Once enable the device charge pumps the gate of the power MOSFET to 5 V gate to source voltage while controlling the slew rate of the turn on time. The mostly constant gate to source voltage keeps the on resistance low through out the input voltage range. When disable, the output discharge circuit turns on to help pull the output voltage to ground more quickly. Also in disable mode, the reverse blocking circuit is activated to prevent current from going back to the input in case the output voltage is higher than the input voltage. Input voltage is needed for the reverse blocking circuit to work properly, it can be as low as $V_{IN(min)}$.

APPLICATION INFORMATION

Input Capacitor

While a bypass capacitor on the input is not required, a 2.2 μ F or larger capacitor for C_{IN} is recommended in almost all applications. The bypass capacitor should be placed as physically close as possible to the SiP32411 to be effective in minimizing transients on the input. Ceramic capacitors are recommended over tantalum because of their ability to withstand input current surges from low impedance sources such as batteries in portable devices.

Output Capacitor

A 0.1 μ F capacitor or larger across V_{OUT} and GND is recommended to insure proper slew operation. C_{OUT} may be increased without limit to accommodate any load transient condition with only minimal affect on the SiP32411 turn on slew rate time. There are no ESR or capacitor type requirement.

Enable

The EN pin is compatible with both TTL and CMOS logic voltage levels.

Protection Against Reverse Voltage Condition

The SiP32411 contains a reverse blocking circuitry to protect the current from going to the input from the output in case where the output voltage is higher than the input voltage when the main switch is off. A supply voltage as low as the minimum required input voltage is necessary for this circuitry to work properly.

Thermal Considerations

The SiP32411 is designed to maintain a constant output load current. Due to physical limitations of the layout and assembly of the device the maximum switch current is 1.8 A

for SC-70-6 package and 2.4 A for TDFN4 package, as stated in the absolute maximum ratings table. However, another limiting characteristic for the safe operating load current is the thermal power dissipation of the package. To obtain the highest power dissipation (and a thermal resistance of 240 $^{\circ}$ C/W for SC-70-6 and 170 $^{\circ}$ C/W for TDFN4) the power pad of the device should be connected to a heat sink on the printed circuit board.

The maximum power dissipation in any application is dependent on the maximum junction temperature, $T_{J(max)} = 125^{\circ}$ C, the junction-to-ambient thermal resistance for the TDFN4 1.2 mm x 1.6 mm package, $\theta_{J-A} = 170^{\circ}$ C/W, and the ambient temperature, T_A , which may be formulaically expressed as:

$$P (max.) = \frac{T_{J(max)} - T_A}{\theta_{J-A}} = \frac{125 - T_A}{170}$$

It then follows that, assuming an ambient temperature of 70 $^{\circ}$ C, the maximum power dissipation will be limited to about 324 mW.

So long as the load current is below the 2.4 A limit, the maximum continuous switch current becomes a function two things: the package power dissipation and the $R_{DS(on)}$ at the ambient temperature.

As an example let us calculate the worst case maximum load current at $T_A = 70^{\circ}$ C. The worst case $R_{DS(on)}$ at 25 $^{\circ}$ C occurs at an input voltage of 1.2 V and is equal to 75 m Ω . The $R_{DS(on)}$ at 70 $^{\circ}$ C can be extrapolated from this data using the following formula

$$R_{DS(on)} (at 70^{\circ}C) = R_{DS(on)} (at 25^{\circ}C) \times (1 + T_C \times \Delta T)$$

Where T_C is 3400 ppm/ $^{\circ}$ C. Continuing with the calculation we have

$$R_{DS(on)} (at 70^{\circ}C) = 75 m\Omega \times (1 + 0.0034 \times (70^{\circ}C - 25^{\circ}C)) = 86.5 m\Omega$$

The maximum current limit is then determined by

$$I_{LOAD(max)} < \sqrt{\frac{P(max.)}{R_{DS(on)}}}$$

which in case is 1.94 A. Under the stated input voltage condition, if the 1.94 A current limit is exceeded the internal die temperature will rise and eventually, possibly damage the device.

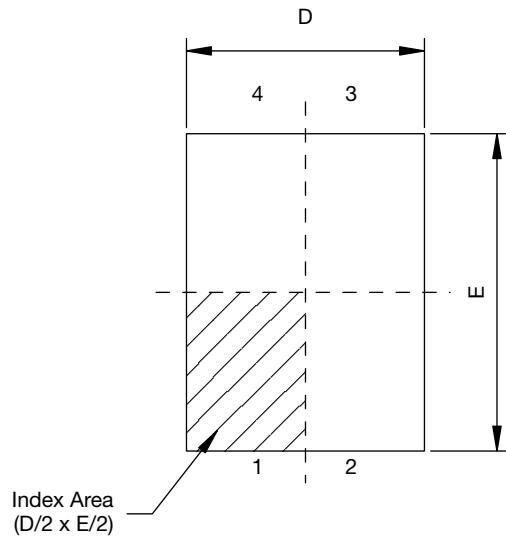


| PRODUCT SUMMARY | | |
|--|---|---|
| Part number | SiP32411 | SiP32411 |
| Description | 1.1 V to 5 V, 62 mΩ, 150 μs rise time, output discharge | 1.1 V to 5 V, 101 mΩ, 150 μs rise time, output discharge |
| Configuration | Single | Single |
| Slew rate time (μs) | 150 | 150 |
| On delay time (μs) | 140 | 140 |
| Input voltage min. (V) | 1.1 | 1.1 |
| Input voltage max. (V) | 5.5 | 5.5 |
| On-resistance at input voltage min. (mΩ) | 66 | 105 |
| On-resistance at input voltage max. (mΩ) | 62 | 101 |
| Quiescent current at input voltage min. (μA) | 6.7 | 6.7 |
| Quiescent current at input voltage max. (μA) | 71 | 71 |
| Output discharge (yes / no) | Yes | Yes |
| Reverse blocking (yes / no) | Yes | Yes |
| Continuous current (A) | 2.4 | 1.8 |
| Package type | TDFN4 | SC-70-6 |
| Package size (W, L, H) (mm) | 1.2 x 1.6 x 0.5 | 2.0 x 2.0 x 0.5 |
| Status code | 2 | 2 |
| Product type | Slew rate | Slew rate |
| Applications | Computers, consumer, industrial, healthcare, networking, portable | Computers, consumer, industrial, healthcare, networking, portable |

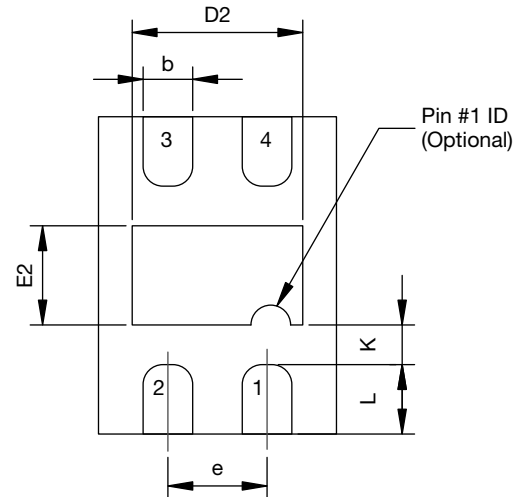
Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?66710.



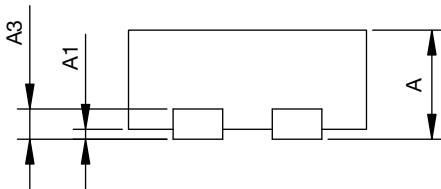
TDFN4 1.2 x 1.6 Case Outline



Top View



Bottom View



Side View

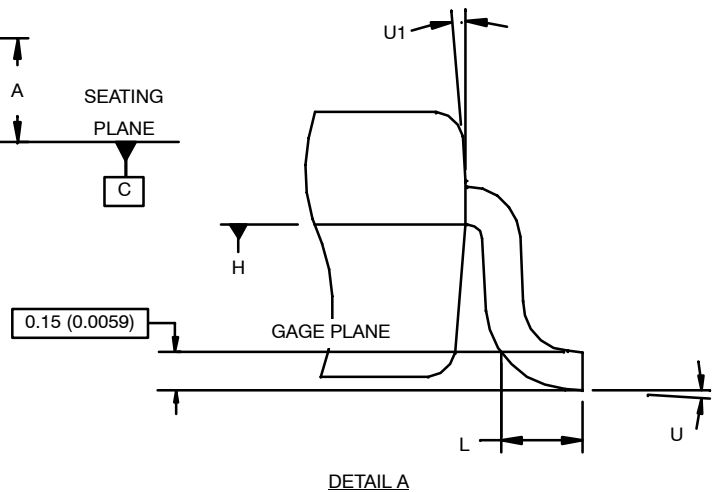
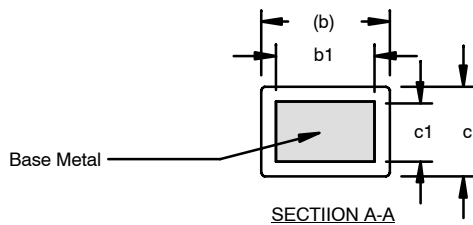
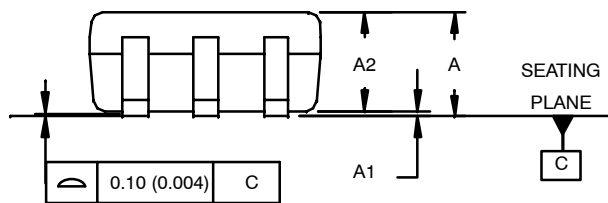
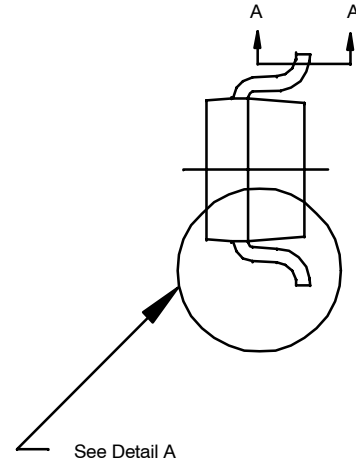
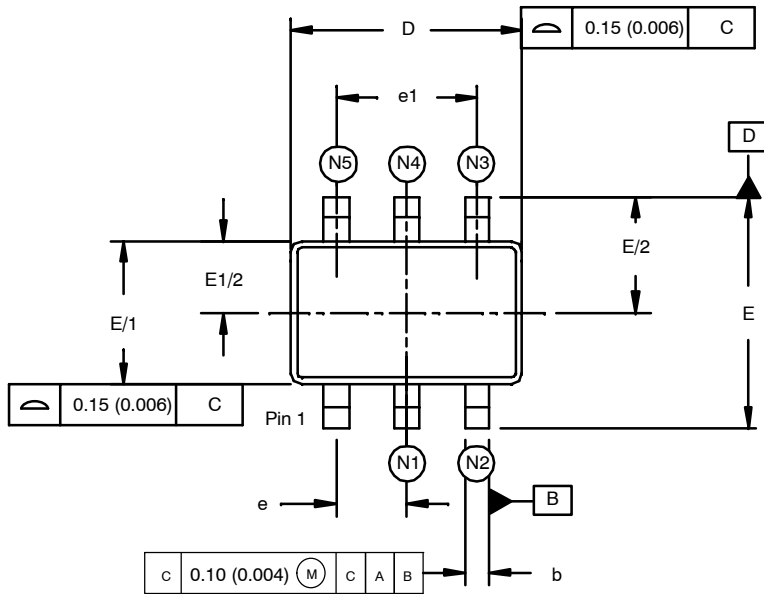
| DIM. | MILLIMETERS | | | INCHES | | |
|------|--|------|------|-------------------------------|-------|-------|
| | MIN. | NOM. | MAX. | MIN. | NOM. | MAX. |
| A | 0.45 | 0.55 | 0.60 | 0.017 | 0.022 | 0.024 |
| A1 | 0.00 | - | 0.05 | 0.00 | - | 0.002 |
| A3 | 0.15 REF. or 0.127 REF. ⁽¹⁾ | | | 0.006 or 0.005 ⁽¹⁾ | | |
| b | 0.20 | 0.25 | 0.30 | 0.008 | 0.010 | 0.012 |
| D | 1.15 | 1.20 | 1.25 | 0.045 | 0.047 | 0.049 |
| D2 | 0.81 | 0.86 | 0.91 | 0.032 | 0.034 | 0.036 |
| e | 0.50 BSC | | | 0.020 | | |
| E | 1.55 | 1.60 | 1.65 | 0.061 | 0.063 | 0.065 |
| E2 | 0.45 | 0.50 | 0.55 | 0.018 | 0.020 | 0.022 |
| K | 0.25 typ. | | | 0.010 typ. | | |
| L | 0.25 | 0.30 | 0.35 | 0.010 | 0.012 | 0.014 |

ECN: T16-0143-Rev. C, 18-Apr-16
DWG: 5995

Note

⁽¹⁾ The dimension depends on the leadframe that assembly house used.

SC-70: 3/4/5/6-LEADS (PIC ONLY)



| Pin Code | LEAD COUNT | | | |
|----------|------------|---|---|---|
| | 3 | 4 | 5 | 6 |
| N1 | - | - | 2 | 2 |
| N2 | 2 | 2 | 3 | 3 |
| N3 | - | 3 | 4 | 4 |
| N4 | 3 | - | - | 5 |
| N5 | - | 4 | 5 | 6 |

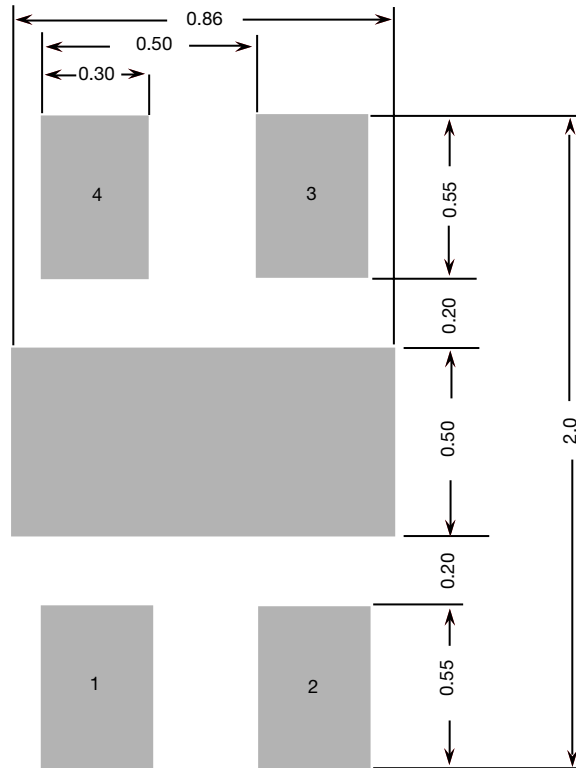
NOTES:

1. Dimensioning and tolerancing per ANSI Y14.5M-1994.
2. Controlling dimensions: millimeters converted to inch dimensions are not necessarily exact.
3. Dimension "D" does not include mold flash, protrusion or gate burr. Mold flash, protrusion or gate burr shall not exceed 0.15 mm (0.006 inch) per side.
4. The package top shall be smaller than the package bottom. Dimension "D" and "E1" are determined at the outer most extremes of the plastic body exclusive of mold flash, tie bar burrs, gate burrs and interlead flash, but including any mismatch between the top and bottom of the plastic body.



| Dim | MILLIMETERS | | | INCHES | | |
|---|-------------|------|------|------------|-------|-------|
| | Min | Nom | Max | Min | Nom | Max |
| A | 0.80 | – | 1.10 | 0.031 | – | 0.043 |
| A1 | 0.00 | – | 0.10 | 0.000 | – | 0.004 |
| A2 | 0.80 | 0.90 | 1.00 | 0.031 | 0.035 | 0.040 |
| b | 0.15 | – | 0.30 | 0.006 | – | 0.012 |
| b1 | 0.15 | 0.20 | 0.25 | 0.006 | 0.008 | 0.010 |
| c | 0.08 | – | 0.25 | 0.003 | – | 0.010 |
| c1 | 0.08 | 0.13 | 0.20 | 0.003 | 0.005 | 0.008 |
| D | 1.90 | 2.10 | 2.15 | 0.074 | 0.082 | 0.084 |
| E | 2.00 | 2.10 | 2.20 | 0.078 | 0.082 | 0.086 |
| E₁ | 1.15 | 1.25 | 1.35 | 0.045 | 0.050 | 0.055 |
| e | 0.65 BSC | | | 0.0255 BSC | | |
| e₁ | 1.30 BSC | | | 0.0512 BSC | | |
| L | 0.26 | 0.36 | 0.46 | 0.010 | 0.014 | 0.018 |
| U | 0° | – | 8° | 0° | – | 8° |
| U1 | 4° | | 10° | 4° | | 10° |
| ECN: S-42145—Rev. A, 22-Nov-04 DWG: 5941 | | | | | | |

RECOMMENDED MINIMUM PADS FOR TDFN4 1.2 x 1.6



Recommended Minimum Pads
Dimensions in mm



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